



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

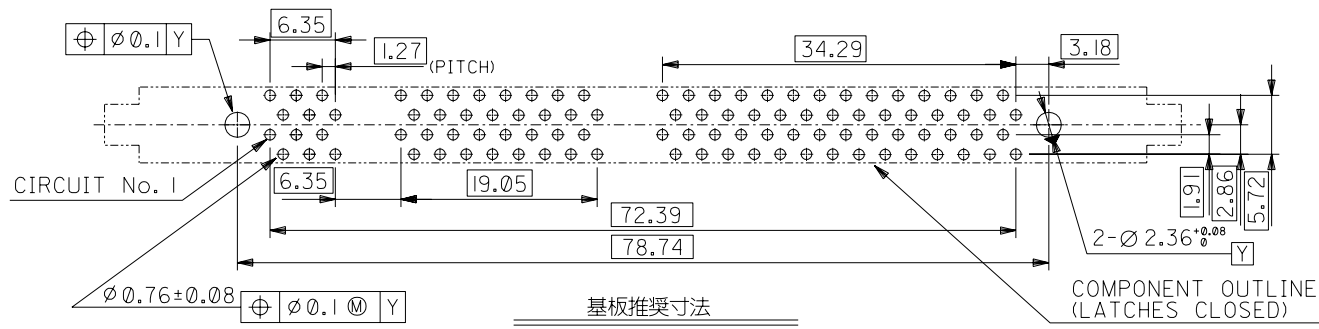
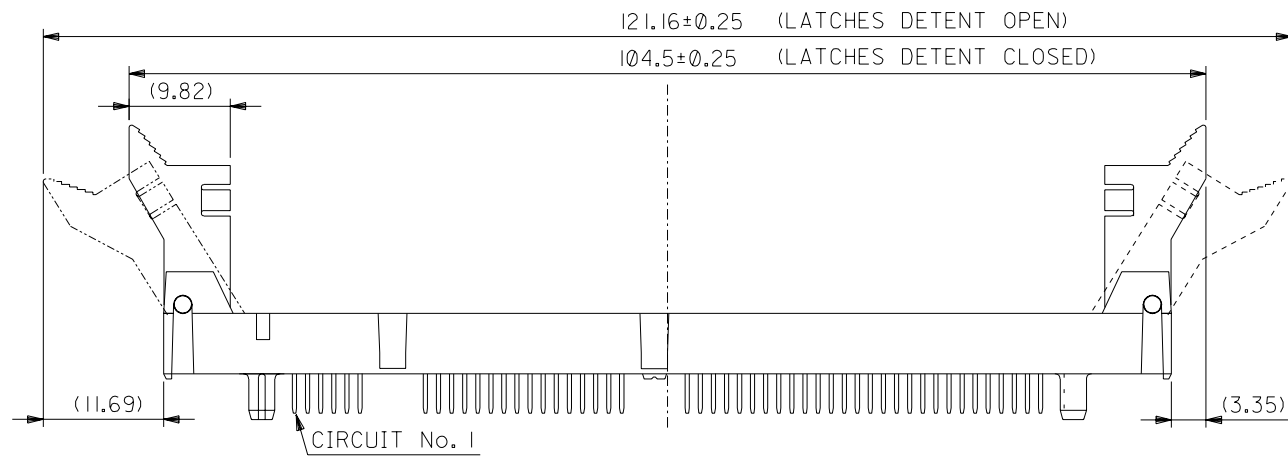
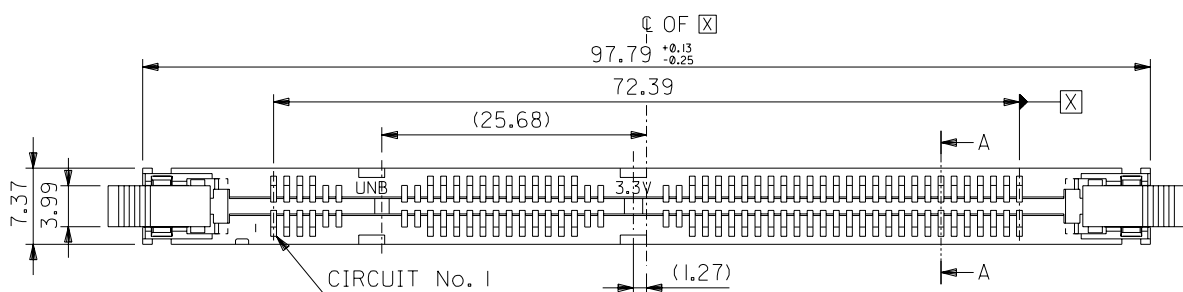
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

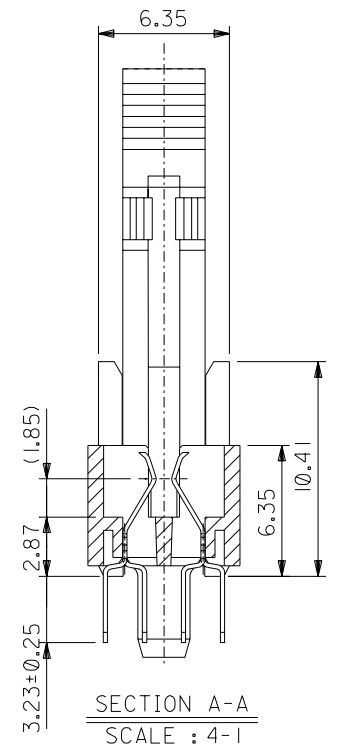
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DWG. NO. SD-71251-5101  
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING



基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT



角度 ANGLE	±3°				
30°以上 OVER	±0.3				
10°以上 OVER 30°未滿 UNDER	±0.25	A	変更 REVISD (J2004-4509)	Y.W.	04/05/31
10°未滿 UNDER	±0.2	∅	新規作成 PROPOSED (JD90709)	Y.H.	98/11/12
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE

材料 MATERIAL  
 注参照 SEE NOTES  
 仕上げ注参照 FINISH SEE NOTES  
 適用電線範囲 WIRE RANGE —  
 被覆外径 INS. RANGE —  
 DRAWN BY '98/11/12 J. Kinata  
 CHK'D BY '98/11/12 H. Saito  
 APP'D BY [Signature]  
 尺度 SCALE 2 - 1

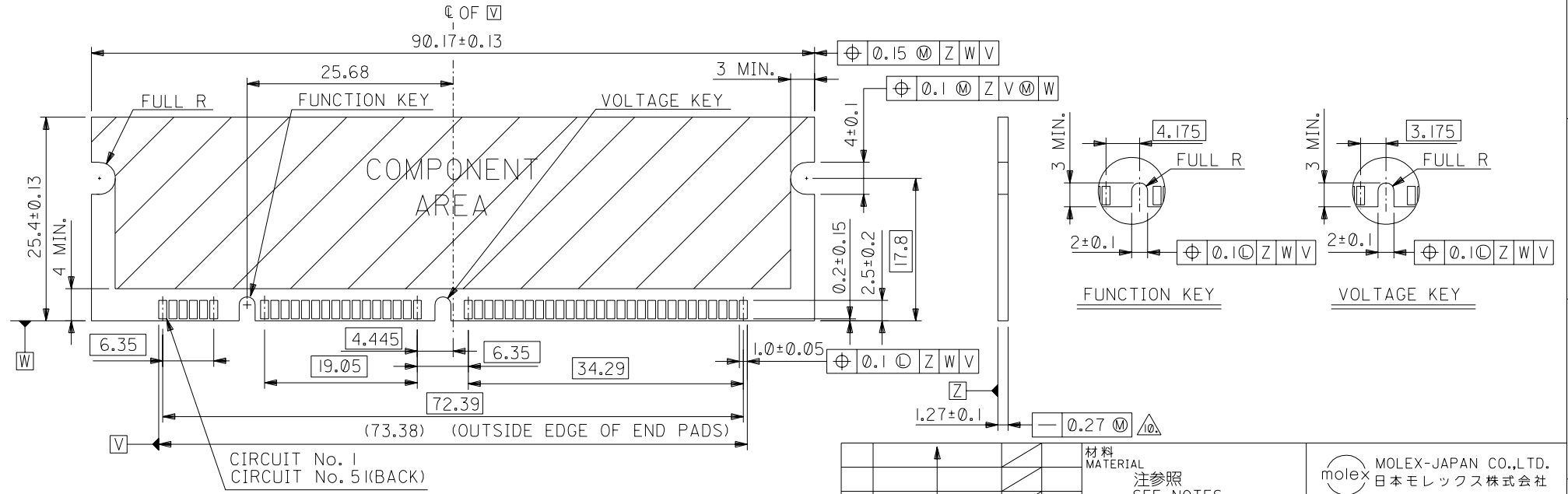
MOLEX-JAPAN CO.,LTD.  
 日本モレックス株式会社  
 REVISE ONLY ON CAD SYSTEM  
 TITLE 名称  
 1.27 PITCH DIMM  
 100 CIRCUIT MULTI-KEY  
 HOUSING ASS'Y  
 -LEAD FREE-  
 DWG. NO. SD-71251-5101 SHEET 1 OF 2 REV A

DWC. NO. SD-71251-5101  
E  
D  
C  
B  
A  
DIMENSIONS IN METRIC DO NOT SCALE DRAWING

NOTE: 1. モジュールの推奨基板厚: 1.27±0.1 (パッド含む)  
CARD SLOT ACCEPTS 1.27±0.1 MODULE THICKNESS. (MEASURED OVER P.C. PADS).  
2. ペグには、基板に対する挿入力が発生します。  
ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.  
3. 製品仕様については、PS-71251-5101をご参照下さい。  
REFER TO PRODUCT SPEC. PS-71251-5101 FOR PERFORMANCE SPECIFICATIONS.  
4. 梱包形態は、トレイ梱包です。  
PRODUCT IS PACKAGED IN TRAYS.  
5. 推奨モジュール・レイアウトはMO-161をご参照下さい。  
RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.  
6. モジュール基板パッドの推奨メッキ仕様  
金: 0.76MICROMETER MIN.  
ニッケル下地: 2.0MICROMETER MIN.  
RECOMMENDED PLATING ON MODULE PADS:  
0.76MICROMETER MIN. HARD GOLD OVER 2.0MICROMETER MIN. NICKEL.

7. 製造日コードはハウジングの側面に刻印されます。  
PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.  
8. 材質  
ハウジング: 耐熱性樹脂 (黒色)  
ラッチ: 耐熱性樹脂 (アイボリー)  
ターミナル: リン青銅  
MATERIALS:  
HOUSING- HIGH-TEMP THERMOPLASTIC COLOR: BLACK  
LATCHES - HIGH-TEMP THERMOPLASTIC COLOR: IVORY  
TERMINAL- PHOSPHOR BRONZE  
9. メッキ仕様  
接点部: 金メッキ0.05-0.25MICROMETER  
パラジウムニッケル下地0.76MICROMETER MIN.  
半田付け部: 錫メッキ 3.8IMICROMETER MIN.  
下地メッキ: ニッケルメッキ1.27MICROMETER MIN.  
PLATING:  
CONTACT AREA: GOLD 0.05-0.25MICROMETER OVER PALLADIUM-NICKEL

SOLDER TAILS: TIN 3.8MICROMETER MIN.  
UNDERPLATE: NICKEL 1.27MICROMETER MIN.  
△モジュール基板の真直度は、底辺より4mmの範囲に適用。  
STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP 4.  
11. 電解メッキなどのために、パッドにタブを設ける場合は、それがコネクタのコンタクト部を損傷する原因とならないよう、ご配慮下さい。  
IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.

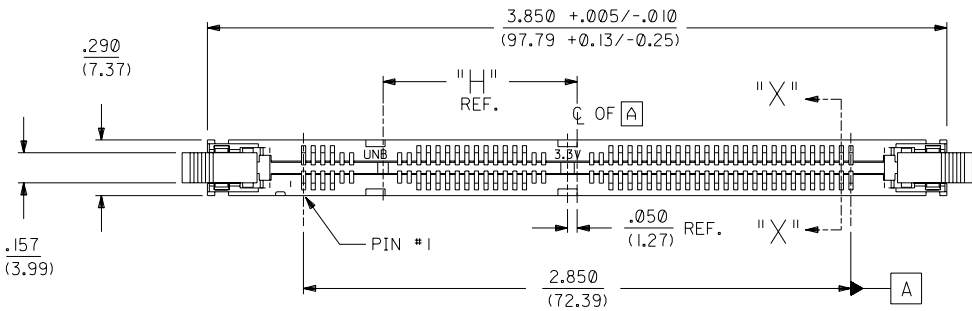


基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT

角度 ANGLE	±3°
30 以上 OVER	+0.3
10 以上 OVER 30 未満 UNDER	+0.25
10 未満 UNDER	+0.2

材料 MATERIAL	注参照 SEE NOTES
仕上げ注参照 FINISH SEE NOTES	
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '98/11/12 J. Kinata	CHK'D BY H. Saito
記号 LTR	変更内容 REVISION RECORD
DR. CHK.	日付 DATE
APP'D BY	尺度 SCALE 2 - 1

材料 MATERIAL	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
注参照 SEE NOTES	
仕上げ注参照 FINISH SEE NOTES	REVISE ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE	TITLE 名称
被覆外径 INS. RANGE	1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-
DRAWN BY '98/11/12 J. Kinata	CHK'D BY H. Saito
記号 LTR	変更内容 REVISION RECORD
DR. CHK.	日付 DATE
APP'D BY	尺度 SCALE 2 - 1
DWG. NO.	SHEET 2 OF 2
SD-71251-5101	REV A



NOTES:

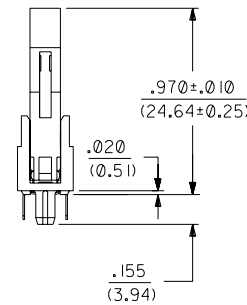
- CARD SLOT ACCEPTS  $.050 \pm .004$  ( $1.27 \pm .10$ ) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
- ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
- REFER TO PRODUCT SPEC. PS-71243 FOR PERFORMANCE SPECIFICATIONS.
- PRODUCT IS PACKAGED IN TRAYS.
- RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.
- RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (AU) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (NI).
- PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

MATERIALS:

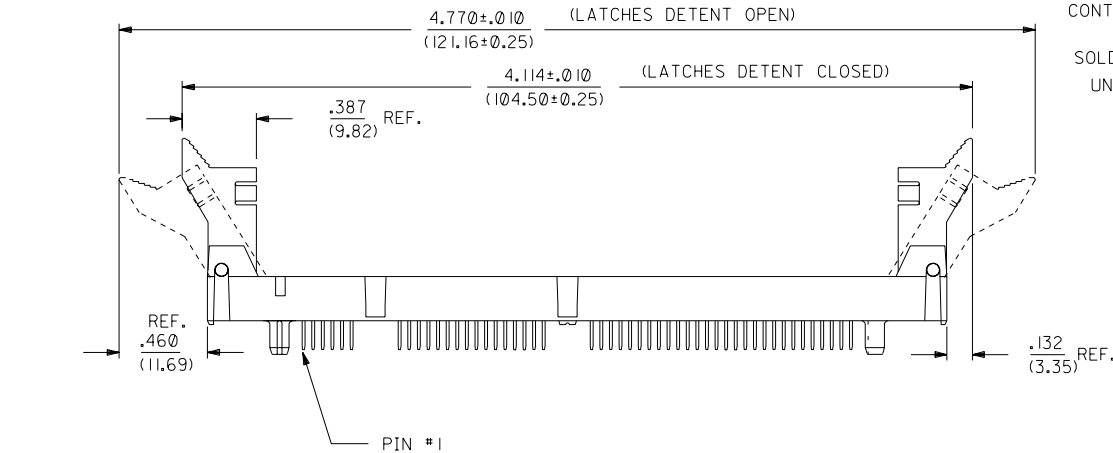
HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.  
 TERMINAL - PHOSPHOR BRONZE  
 LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

PLATING:

CONTACT AREA: MOLEX EBI LUBRICANT OVER  
 GOLD (AU): THICKNESS=10 MICROINCH/(0.25 MICROMETER) MINIMUM.  
 SOLDER TAILS: TIN (Sn): THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.  
 UNDERPLATE: NICKEL (NI) OVER ENTIRE CONTACT.



NOTE FOR LEAD FREE CONVERSION:  
 THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



71251-5101 SHOWN

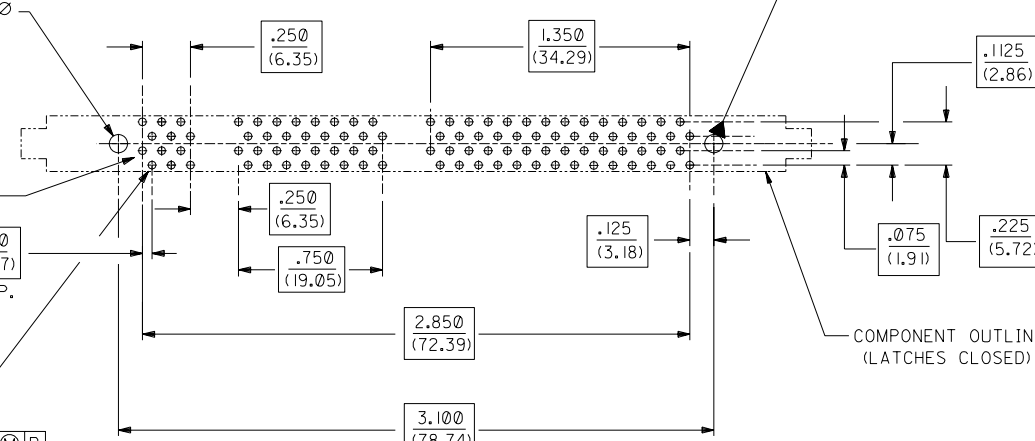
$\oplus \ominus \ .004 / (0.10) \ B \ 2 \ PL$

$.093 \pm .003 / - .000$   
 (2.36 +0.08/-0.00)  $\emptyset$   
 2 PL

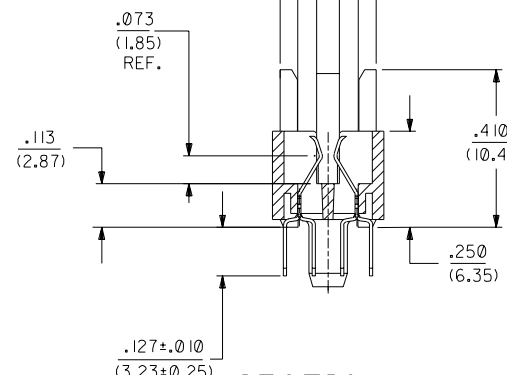
$.050$   
 (1.27) TYP.

$.030 \pm .003$   
 (0.76 ± 0.08) TYP.

$\oplus \ominus \ .004 / (0.10) \ B$



RECOMMENDED  
 P.C. BOARD HOLE PATTERN  
 (CONNECTOR SIDE)



SECTION "X-X"

SCALE 4:1

2	A1		
1	C1	1	
MFG, SH.	REV.	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		TITLE	
3 PLATE ± .005	---	.050 PITCH DIMM	
2 PLATE ± --- ± 0.13	---	100 CKT MULTI-KEY	
1 PLATE --- ± 0.25	---	SALES DRAWING	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED	SHEET NO. DATE
		60532	1 OF 2 03/26/96
DRWG. BY: JCL		CHK'D BY: DCB	SCALE: 2:1
APPR'D BY: DCB		FILE NAME: ST125151.DGN	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

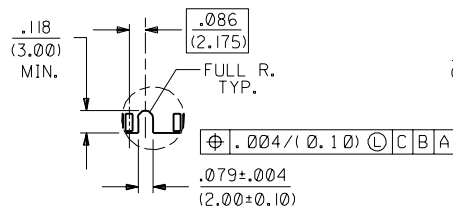
C1	ADD LEAD FREE NOTE ECN# UCP2004-1732 DMORGAN 04/03/09
C	CHANGE PLATING ECN# UDT2002-0712 DMORGAN 02/01/22
B	CHG Sn-Pb THICKNESS ECN# UDT1999-0454 DMORGAN 99/08/09
A1	REVISED PER ECR# U80435 97-8-8 LAURX
A	REVISED PER ECR# U70042 96-7-23 LAURX
2	REVISED PER ECR# U61257 4-10-96 JCL
	X-RELEASE PER ECR# U61175 3-26-96 JCL

71251

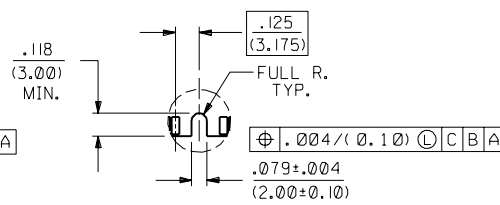
PART NUMBER	DESCRIPTION	FUNCTION KEY	VOLTAGE KEY	DIM. "H"
71251-5101	3.3 VOLT UNBUFFERED	OFFSET RIGHT	CENTER	.1011 (25.68)
71251-5102	5.0 VOLT UNBUFFERED	OFFSET RIGHT	OFFSET LEFT	.1011 (25.68)

NOTES:

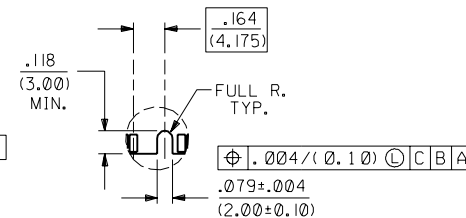
1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP .157/(4.00).
2. IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



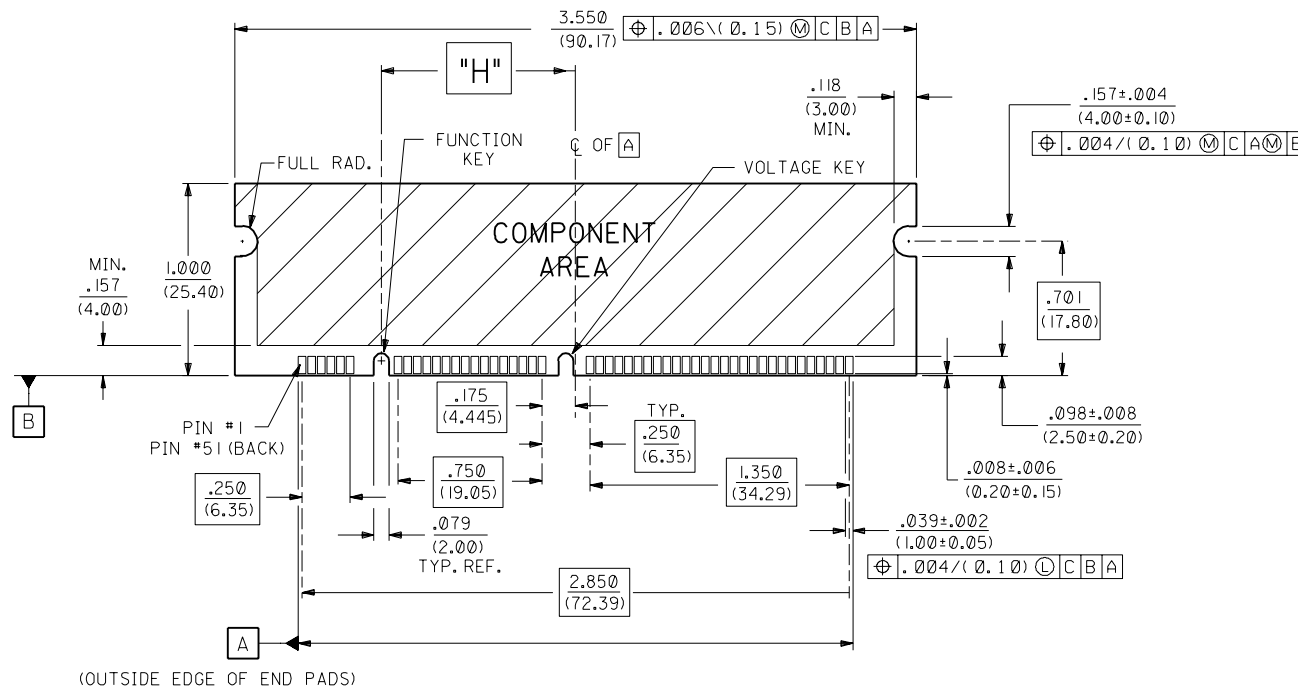
OFFSET LEFT KEY



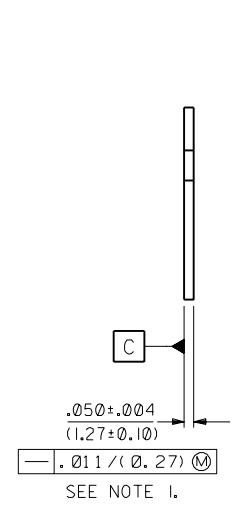
CENTERED KEY



OFFSET RIGHT KEY



RECOMMENDED MODULE LAYOUT  
100 CKT 3.3V UNBUFFERED



REV.	DESCRIPTION
A1	SEE SHEET 1
A	SEE SHEET 1
2	SEE SHEET 1
1	SEE SHEET 1

DIMENSIONS SHOWN (METRIC) INCH		UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°		TITLE	
3 PLACE	±	INCH	METRIC		
3 PLACE	±	.005	---	.050 PITCH DIMM	
2 PLACE	±	.01	± 0.13	100 CKT MULTI-KEY	
1 PLACE	---	---	± 0.25	SALES DRAWING	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MFG. SH. REV. LTR. REVISIONS	
DRAWN BY: JCL		CHK'D BY: DCB		PART NO. SEE CHART SDA-71251-5***	
APP'D BY: DCB		SCALE: 2: 1		FILE NAME: 5725152.DWG	
				SHEET NO. 2	
				DATE: 03/26/96	
				MOLEX INCORPORATED U.S.A.	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	